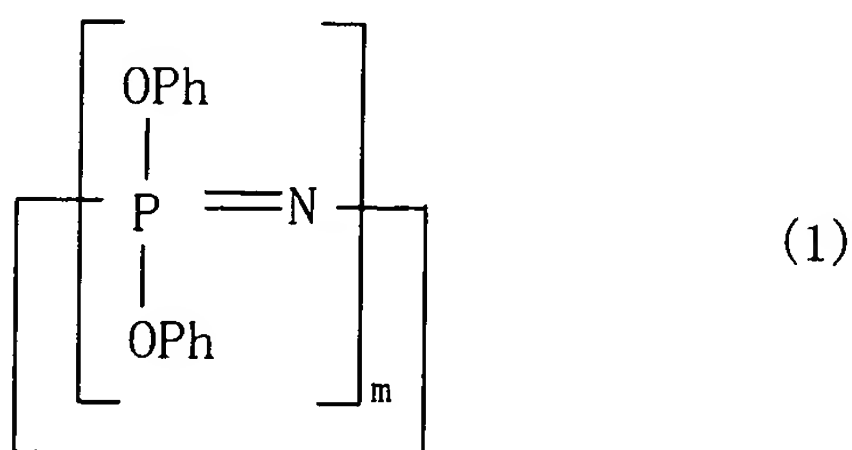
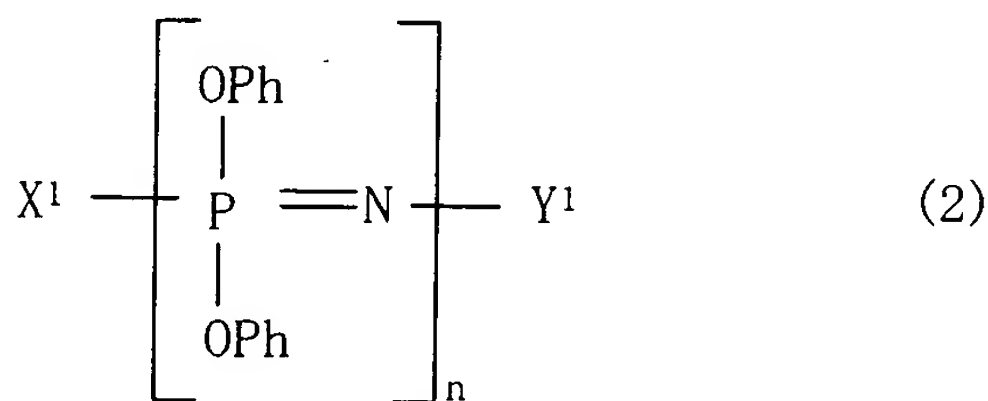


WHAT IS CLAIMED IS:

1. A heat-resistant composition containing solvent-soluble polyimide resin (A) and a phosphazene compound (B), wherein said phosphazene compound (B) includes at least either a cyclic phenoxyphosphazene compound (B1) expressed in the following chemical formula (1):

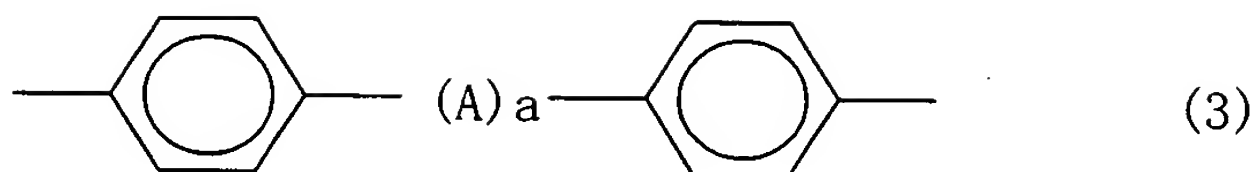


where  $m$  represents an integer of 3 to 25 and Ph represents a phenyl group, or a chain phenoxyphosphazene compound (B2) expressed in the following chemical formula (2):



where  $\text{X}^1$  represents group  $-\text{N} = \text{P}(\text{OPh})_3$  or group  $-\text{N} = \text{P}(\text{O})\text{OPh}$ ,  $\text{Y}^1$  represents group  $-\text{P}(\text{OPh})_4$  or group  $-\text{P}(\text{O})(\text{OPh})_2$ ,  $n$  represents an integer of 3 to 10,000 and Ph represents a phenyl group,

or a cross-linked phenoxyphosphazene compound (B3) cross-linked by a cross-linking group including at least one of an o-phenylene group, an m-phenylene group, a p-phenylene group and a bisphenylene group expressed in the following chemical formula (3):



20 where A represents  $-\text{C}(\text{CH}_3)_2-$ ,  $-\text{SO}_2-$ ,  $-\text{S}-$  or  $-\text{O}-$  and a represents 0 or 1, with respect to said phosphazene compound including at least either said cyclic phenoxyphosphazene compound (B1) or said chain

25 phenoxyphosphazene compound (B), so that said cross-linking group intervenes between two oxygen atoms desorbed by said phenyl group of said phosphazene compound and the phenyl group content is 50 to 99.9 % with reference to the total number of phenyl groups contained in said phosphazene compound including at least said cyclic phenoxyphosphazene compound (B1) or said chain

30 2. The heat-resistant composition according to claim 1, wherein said polyimide resin (A) is polyimide resin, containing a solvent solubility imparting component selected from at least one of an aliphatic compound component, an alicyclic compound component and an alkylene oxide adduct component of a bisphenol compound, soluble in a solvent containing a low-boiling solvent.

3. The heat-resistant composition according to claim 1, containing a reactive compound (C) selected from at least one of an epoxy compound, an acrylic compound and an isocyanate compound.

4. The heat-resistant component according to claim 1, wherein said polyimide resin (A) is polyamide imide resin, and said reactive compound (C) is an epoxy compound.

5. The heat-resistant composition according to claim 1, wherein said polyimide resin (A) is polyester imide resin, and said reactive compound (C) is an epoxy compound.

6. The heat-resistant composition according to claim 1, wherein said polyimide resin (A) is polyether imide resin, and said reactive compound (C) is an epoxy compound.

7. An adhesive for a printed wiring board employing the heat-resistant composition according to claim 1.

8. An adhesive sheet for a printed wiring board employing the heat-resistant composition according to claim 1.

9. A multilayer printed wiring board employing the heat-resistant composition according to claim 1.

10. A sealant for a printed wiring board employing the heat-resistant composition according to claim 1.

11. An insulating circuit protective film for a printed wiring board employing the heat-resistant composition according to claim 1.

12. A circuit protective agent employing the heat-resistant composition according to claim 1.

13. A cover-lay film employing the heat-resistant composition according to claim 1.

14. A cover ink employing the heat-resistant composition according to claim 1.

15. A substrate for a printed wiring board employing the heat-resistant composition according to claim 1.

16. A metal-clad laminate employing the heat-resistant composition according to claim 1.

17. A conductive paste for a printed wiring board employing the heat-resistant composition according to claim 1.

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